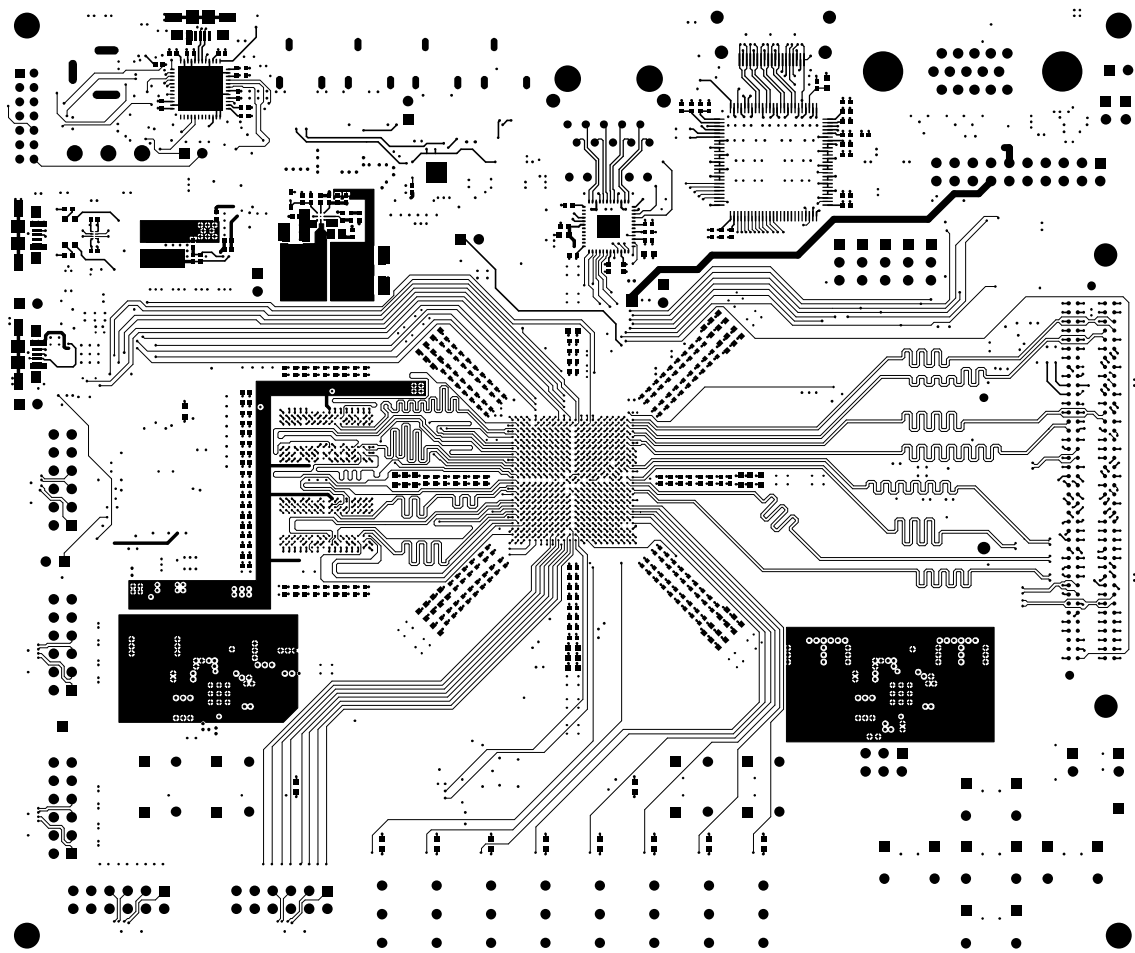
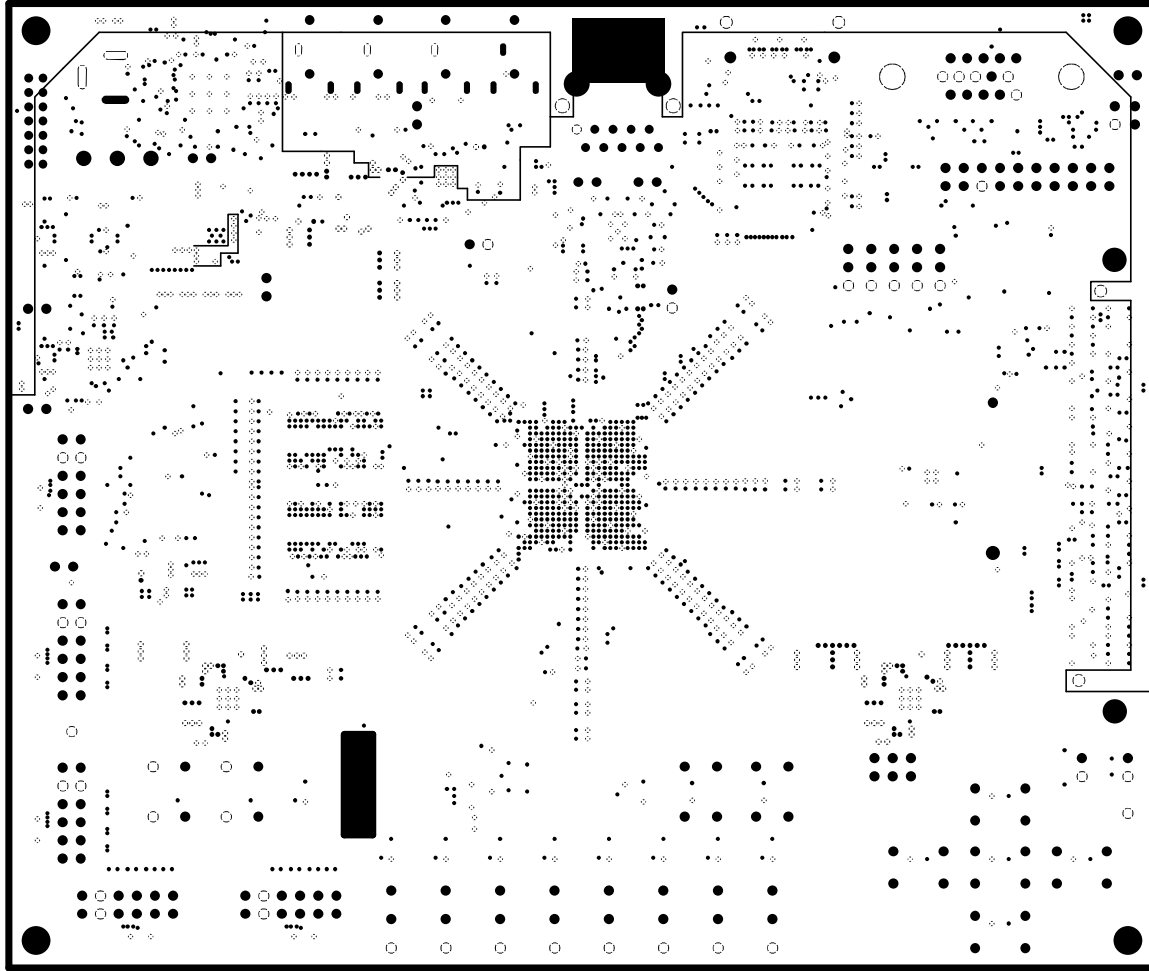
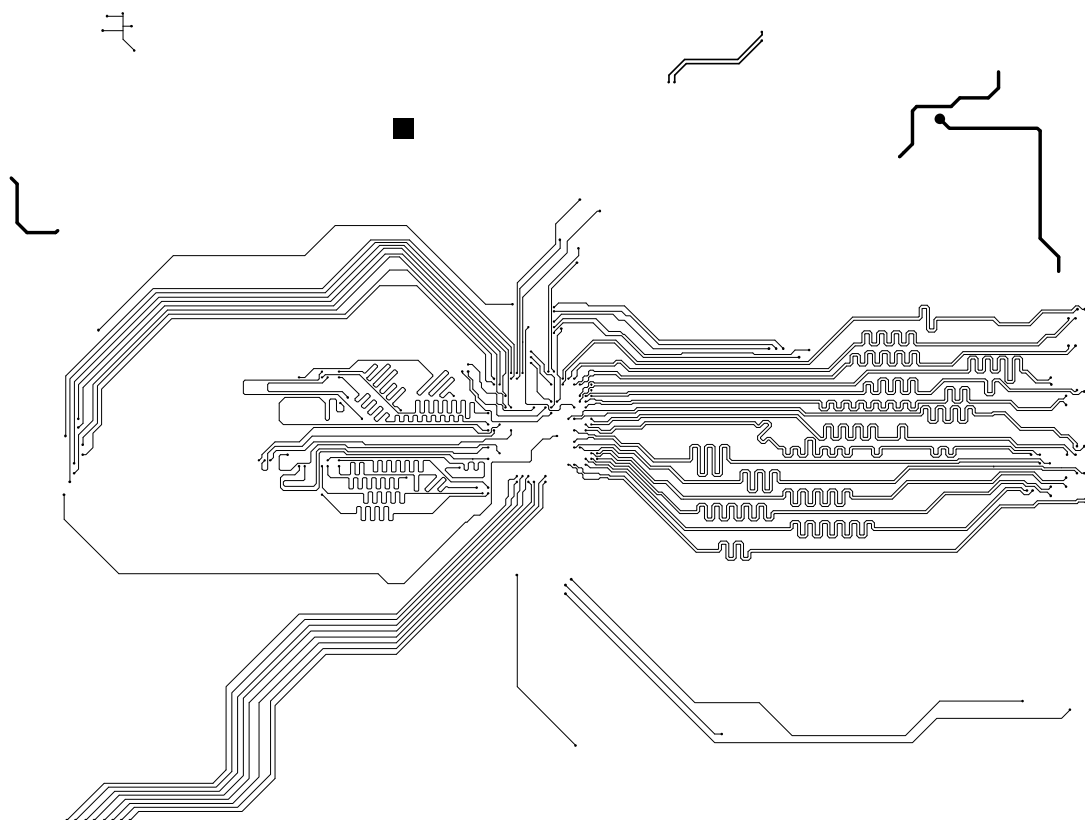


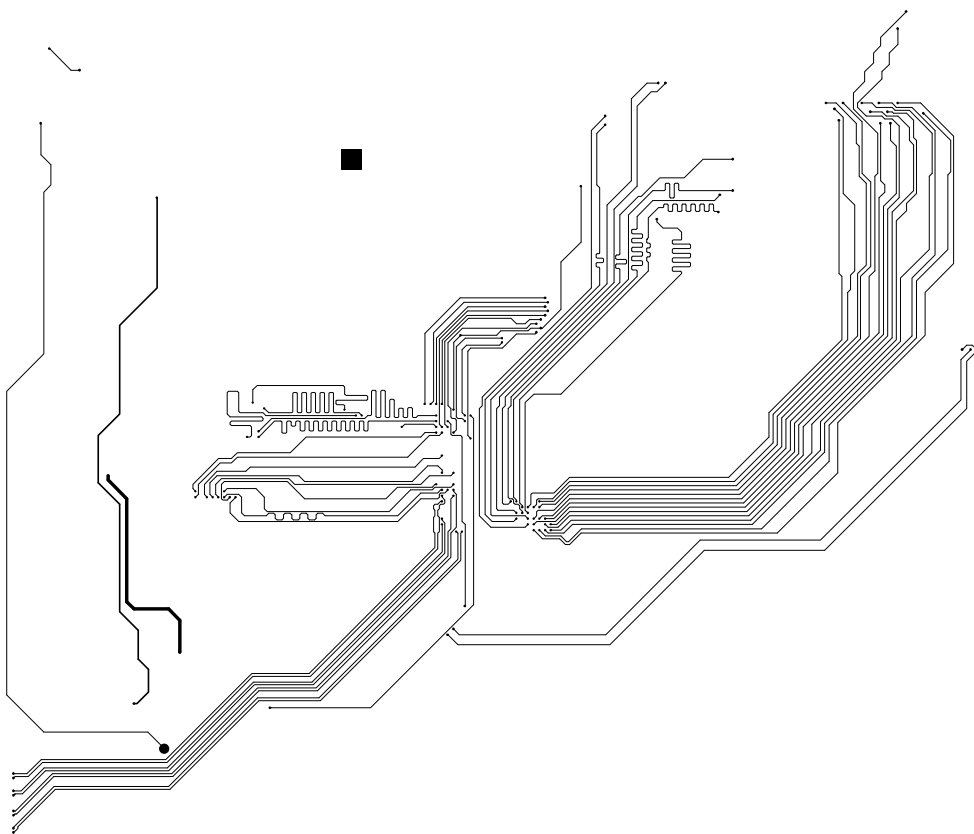
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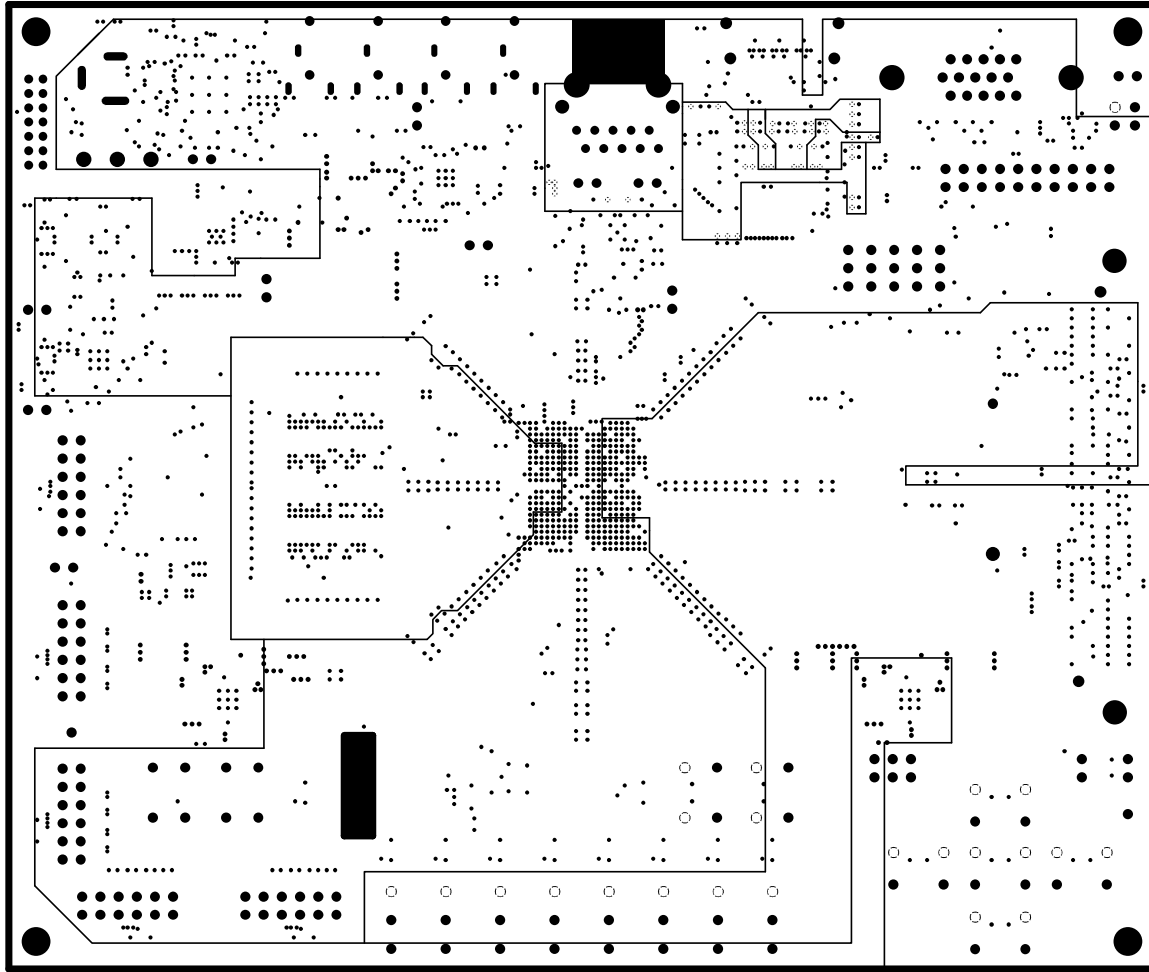
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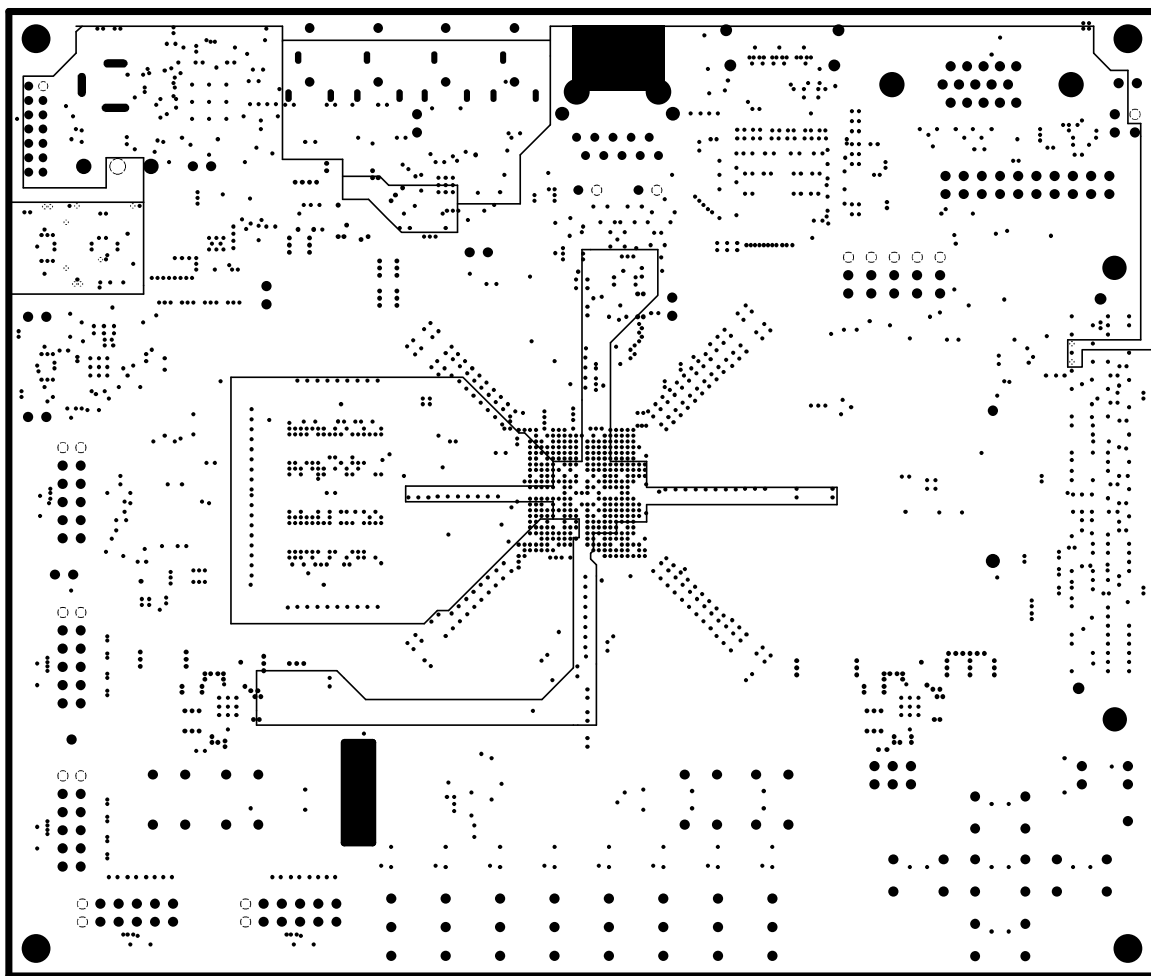


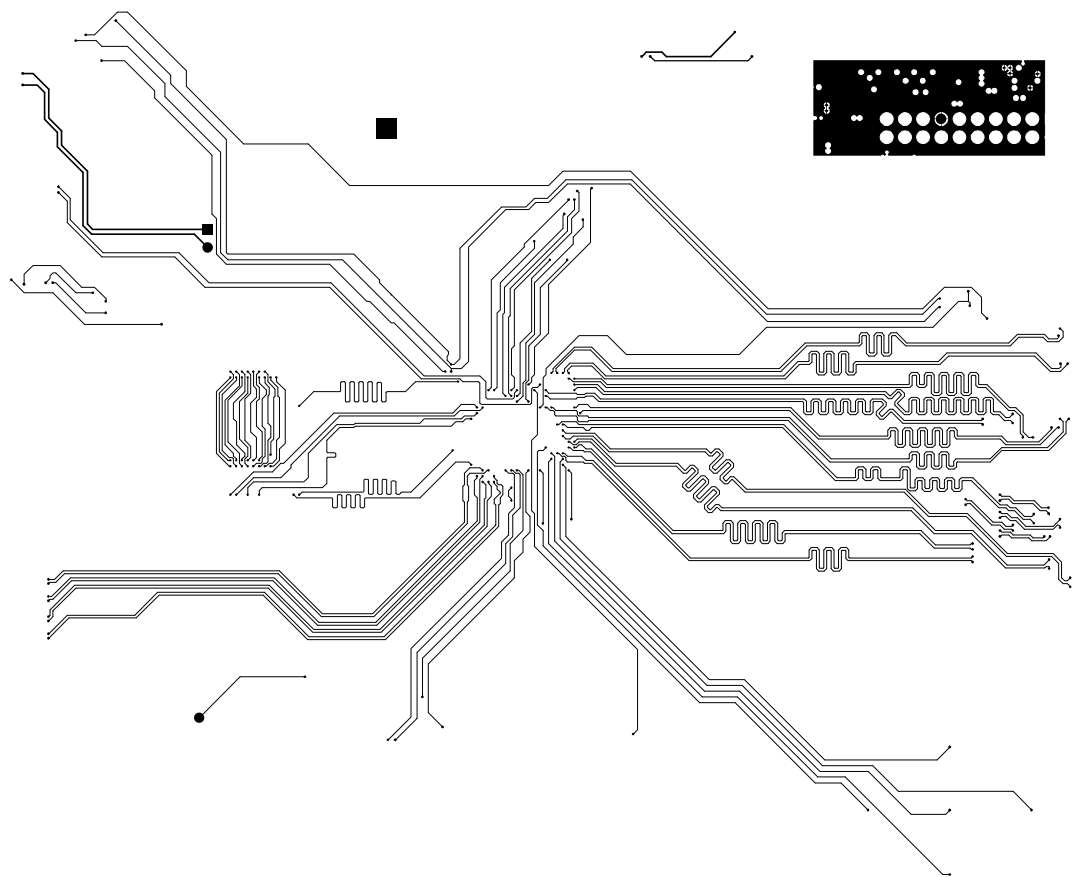


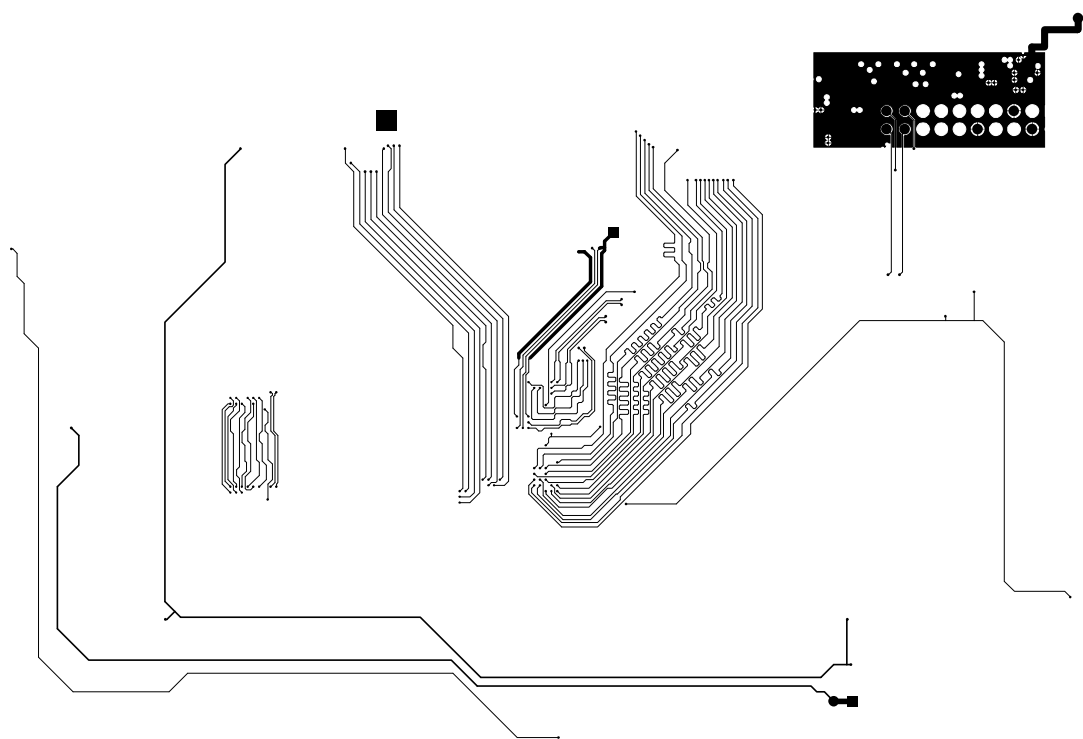


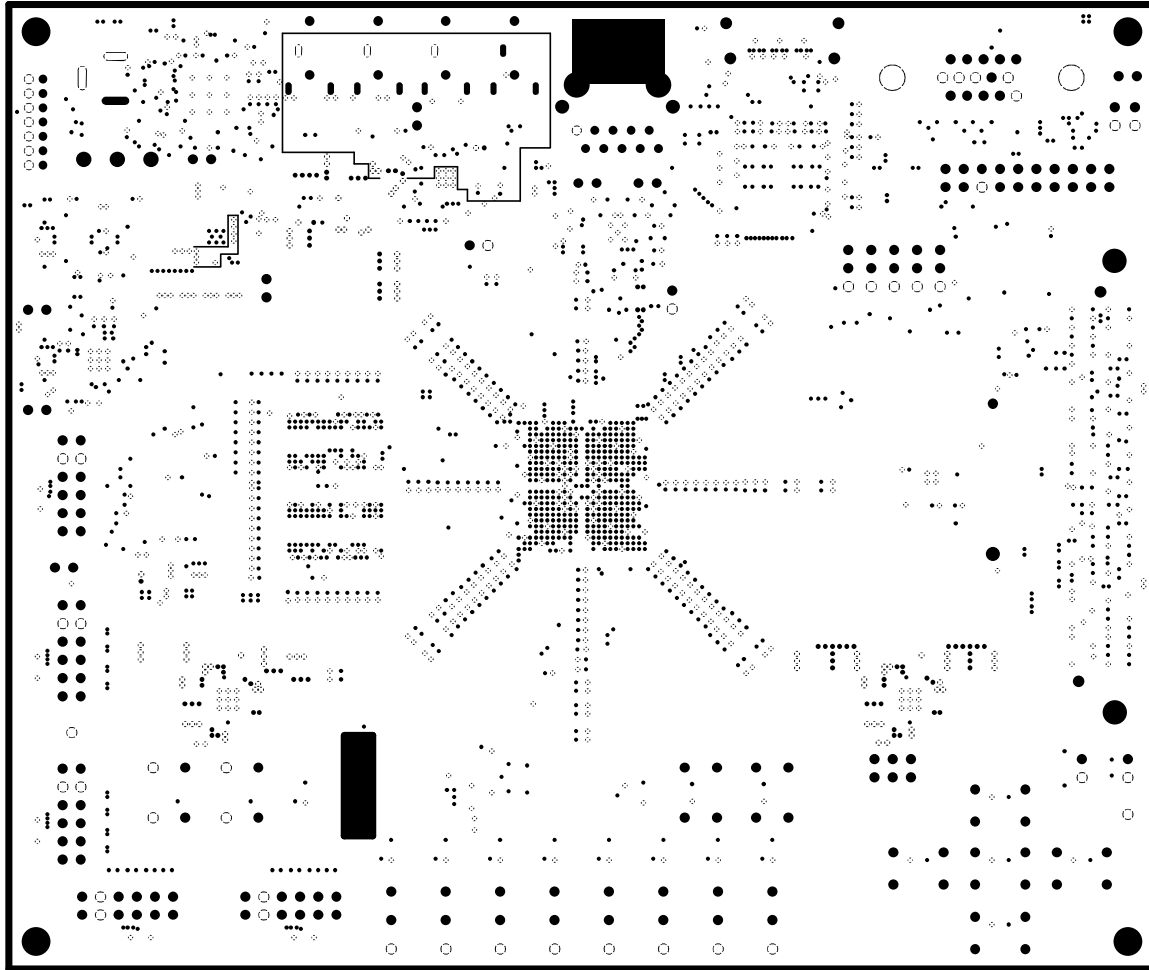


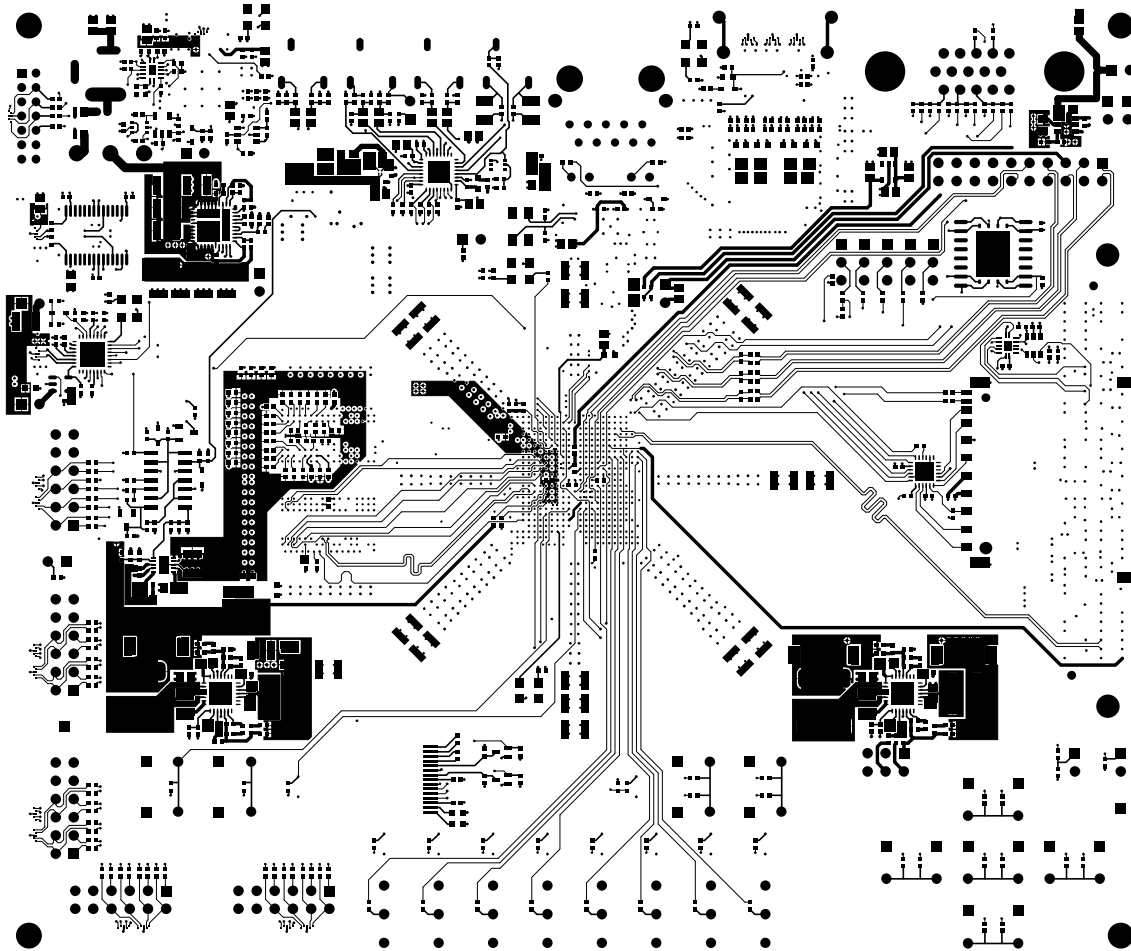


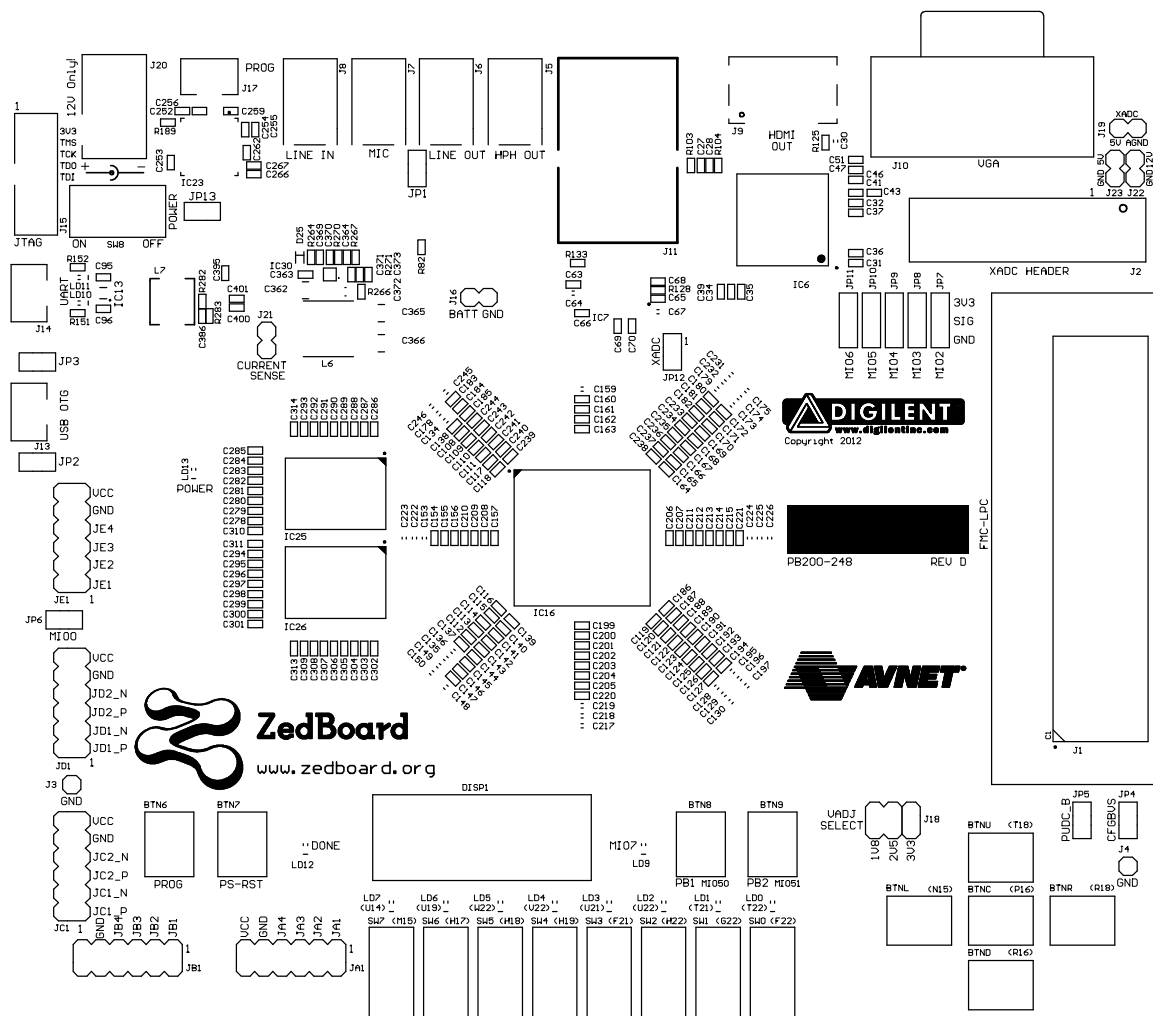


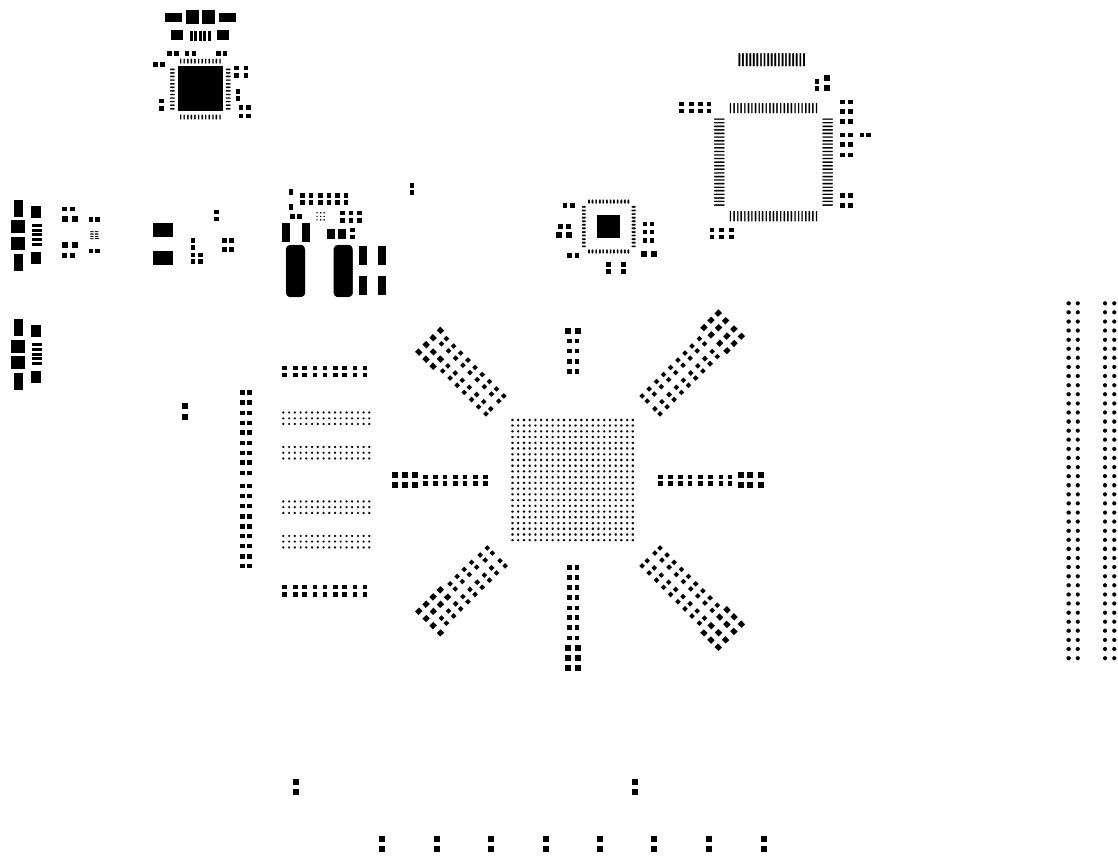


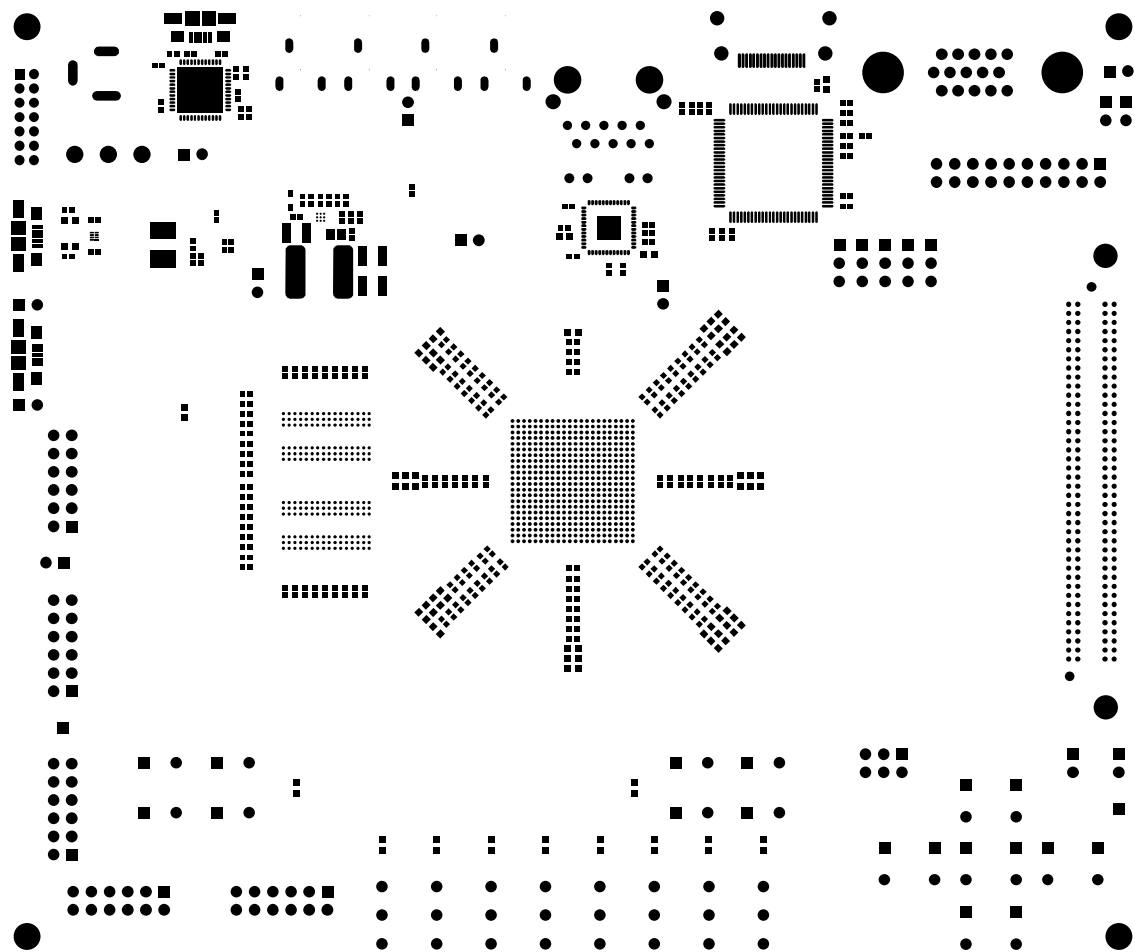


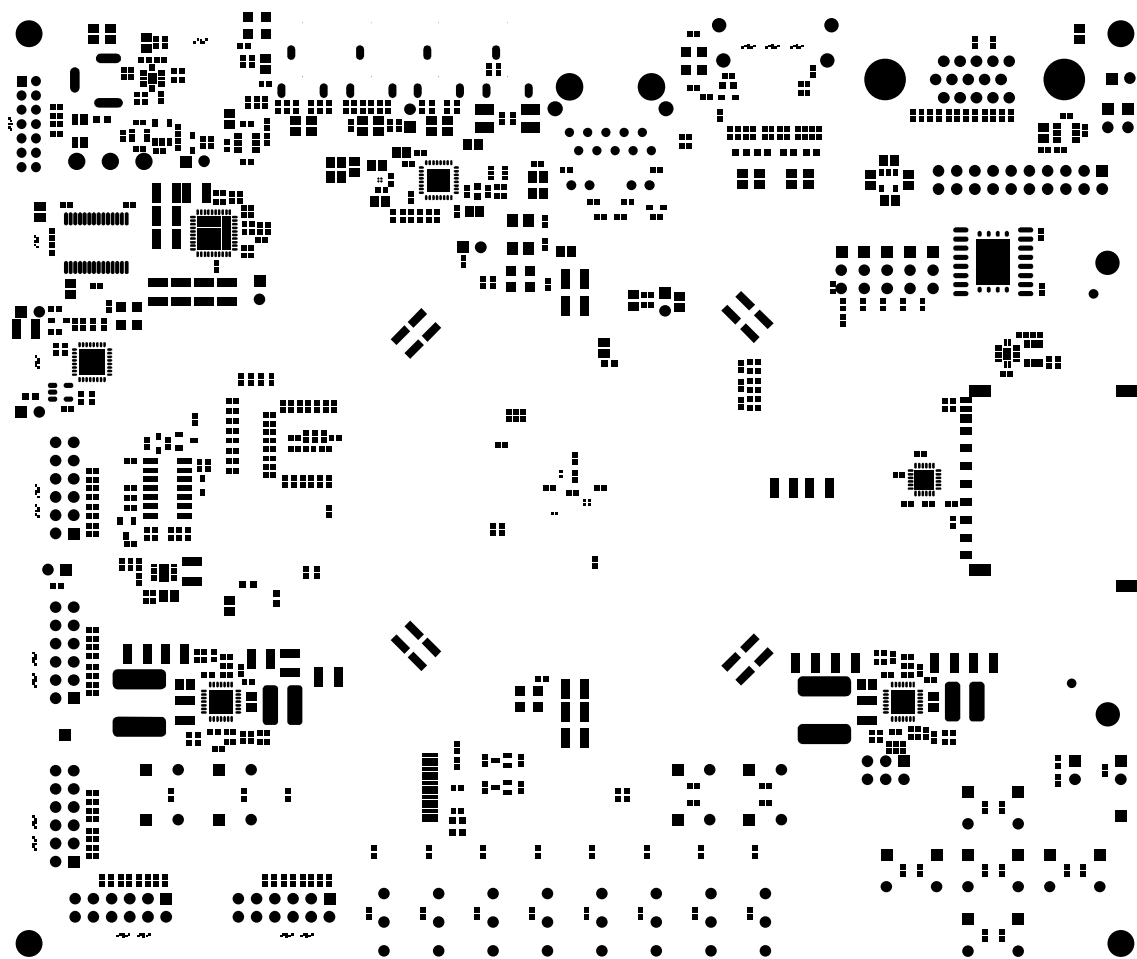


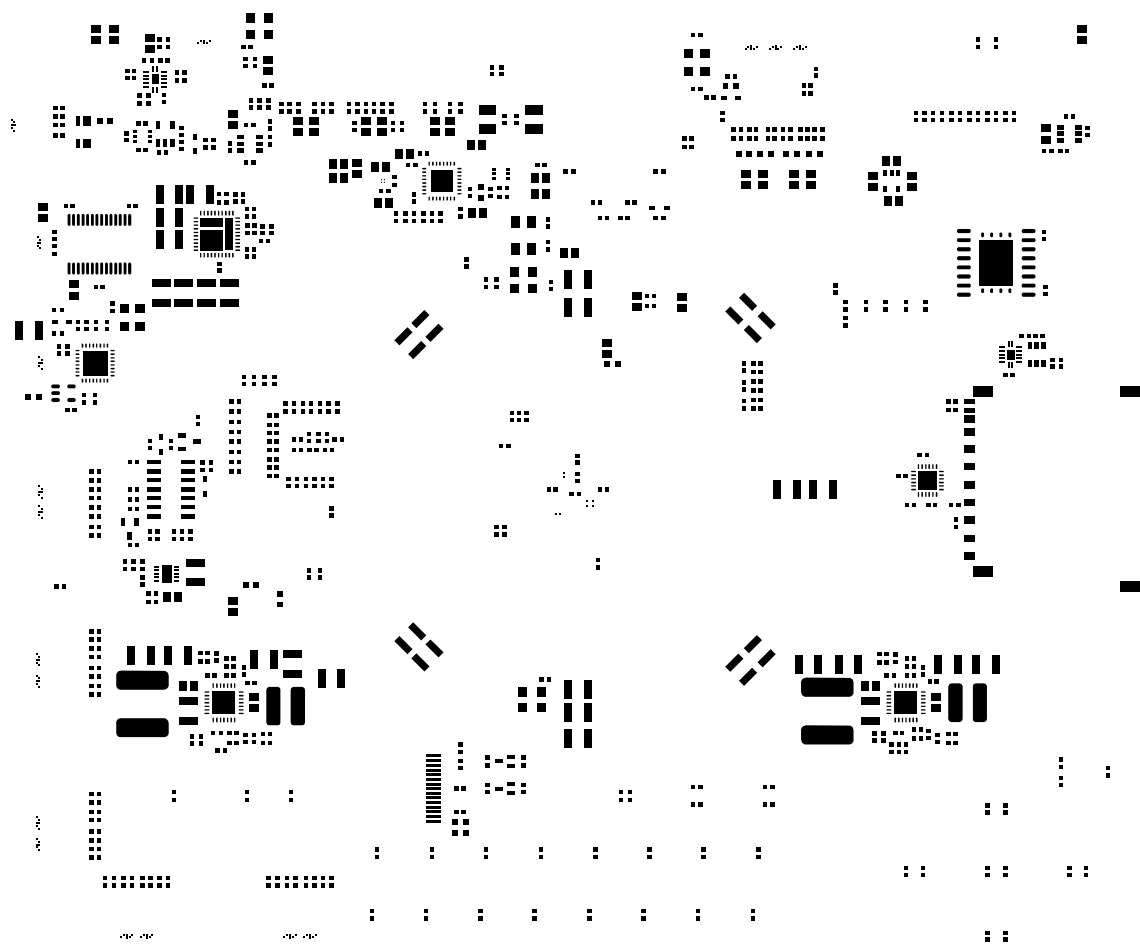


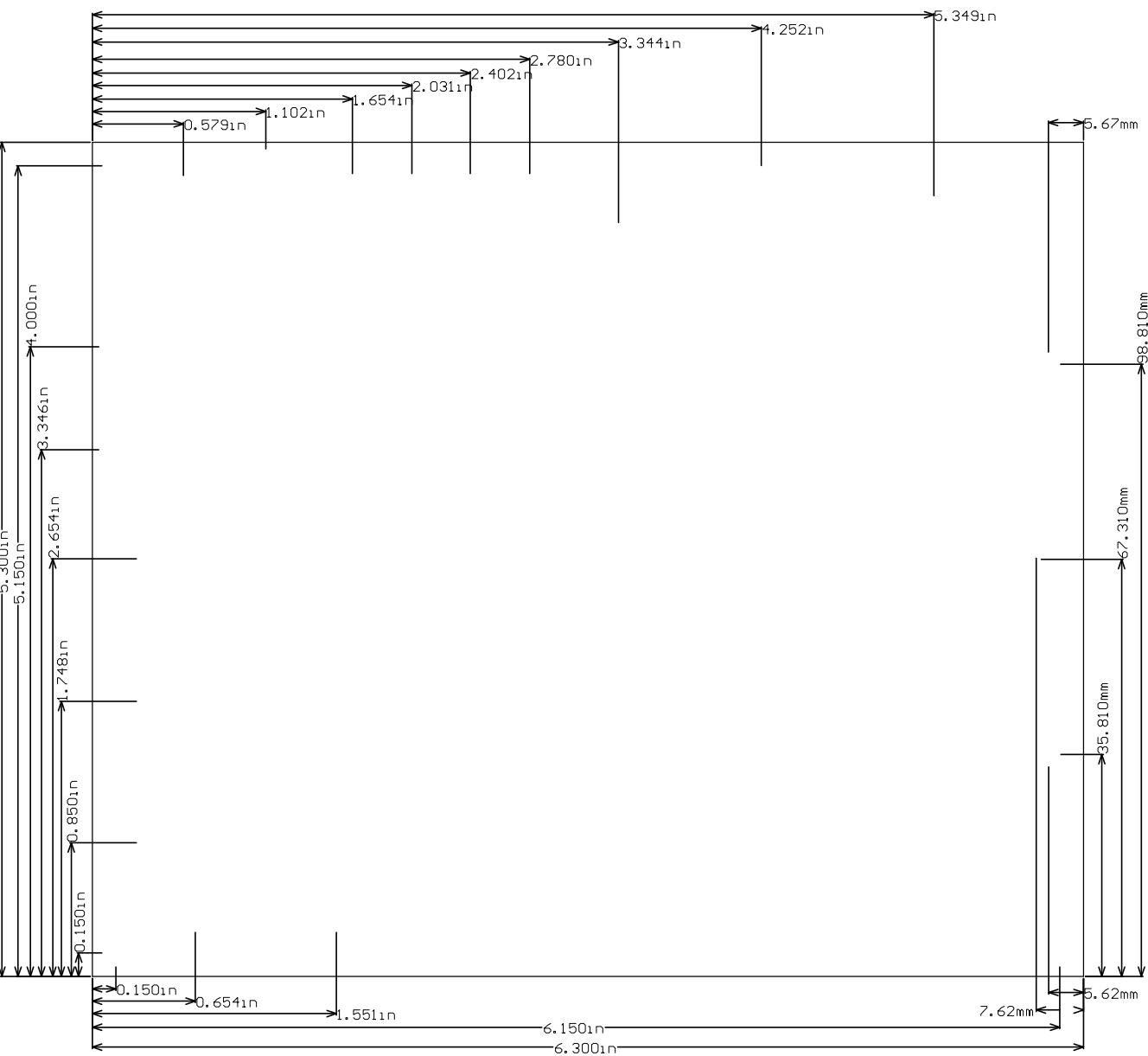












Layer Stack Up Detail for: ZED.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.0102mm	Solder Resist	3.50	
Top Layer	(.GTL)	0.0356mm				
GND2	(.GP1)	0.0356mm	0.1mm	FR-4	4.80	Core
Mid-Layer 1	(.G1)	0.017mm	0.125mm	FR-4	4.80	PrePreg
Mid-Layer 2	(.G2)	0.017mm	0.125mm	FR-4	4.80	Core
POWER1	(.GP2)	0.0356mm	0.35mm	FR-4	4.80	PrePreg
POWER2	(.GP3)	0.0356mm	0.125mm	FR-4	4.80	Core
MidLayer 3	(.G3)	0.017mm	0.125mm	FR-4	4.80	PrePreg
Mid-Layer 4	(.G4)	0.017mm	0.125mm	FR-4	4.80	Core
GND7	(.GP4)	0.0356mm	0.1mm	FR-4	4.80	Core
Bottom Layer	(.GBL)	0.0356mm				
Bottom Solder Mask	(.GBS)		0.0102mm	Solder Resist	3.50	

